

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Name MX150 RCPT 0.3 GOLD 22AWG B WIND UNSLD

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
MX150 RCPT 0.3 GOLD 22AWG B WIND UNSLD	Component		100	0.434996
HSM Copper Unplated	Material		99.3112	0.432
Copper	Substance	7440-50-8	97.3746	0.423576
Nickel	Substance	7440-02-0	0.9931	0.00432
Tin	Substance	7440-31-5	0.8938	0.003888
Phosphorus	Substance	7723-14-0	0.0497	0.000216
Gold Plating	Material		0.0365	0.000159
Cobalt	Substance	7440-48-4	9E-05	4E-07
Nickel	Substance	7440-02-0	9E-05	4E-07
Gold	Substance	7440-57-5	0.0363	0.000158
Tin Plating	Material		0.1236	0.000538
Tin	Substance	7440-31-5	0.1236	0.000538
Nickel Plating	Material		0.5287	0.0023

Form Rev - F

Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Nickel	Substance	7440-02-0	0.5287	0.0023
Further Additives, not to declare	Substance	system	5E-05	2E-07

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

Not reviewed

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Form Rev - F

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead		*Note	500	Yes
nickel powder [particle diameter < 1 mm]	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
nickel powder [particle diameter < 1 mm]	High Copper Alloy (NB109)	*Note	10,000	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
silver	High Copper Alloy (NB109)	*Note	500	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
copper	High Copper Alloy (NB109)	*Note	977,000	Yes

^{*}Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

Part Name	Exemption
	44 Concentration within acceptable GADSL limits
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	34 Not applicable
High Copper Alloy (NB109)	34 Not applicable
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Mar 24, 2021